

AMENDMENTS TO THE CLAIMS

Please amend the Claims as follows. Insertions are shown underlined while deletions are ~~struck through~~.

1 (currently amended): A dicing/die-bonding film comprising a pressure-sensitive adhesive layer (2) on a supporting base material (1) and a die-bonding adhesive layer (3) on the pressure-sensitive adhesive layer (2),

wherein a releasability in an interface between the pressure-sensitive adhesive layer (2) and the die-bonding adhesive layer (3) is different between an interface (A) corresponding to a work-attaching region (3a) in the die-bonding adhesive layer (3) and an interface (B) corresponding to a part or a whole of ~~the other a~~ region (3b) other than the work-attaching region, and the releasability of the interface (A) is higher than the releasability of the interface (B).

2 (currently amended): The dicing/die-bonding film according to claim 1, wherein ~~an~~ adhesion of the pressure-sensitive adhesive layer (2) to the die-bonding adhesive layer (3) is different between a region (2aa) corresponding to the work-attaching region (3a) in the die-bonding adhesive layer (3) and a region (2bb) corresponding to a part or the whole of the other region (3b), and satisfies the relationship:

the adhesion of the ~~pressure-sensitive adhesive layer (2a)~~ region (a) is lower than the adhesion of the ~~pressure-sensitive adhesive layer (2b)~~ region (b).

3 (currently amended): The dicing/die-bonding film according to claim 1, wherein ~~an~~ adhesion of the work-attaching region (3a) in the die-bonding adhesive layer (3) to a work and to the ~~pressure-sensitive adhesive layer (2a)~~ region (a) satisfies the relationship:

the adhesion to the work is higher than the adhesion to the ~~pressure-sensitive adhesive layer (2a)~~ region (a).

4 (currently amended): The dicing/die-bonding film according to claim 1, wherein the part of the region (3b) other than the work-attaching region (3a) in the die-bonding adhesive layer (3) is a dicing ring-attaching region (3b').

5 (currently amended): The dicing/die-bonding film according to claim 4, wherein ~~an~~ adhesion of the dicing ring-attaching region (3b') in the die-bonding adhesive layer (3) to ~~the a~~ dicing ring and to the ~~pressure-sensitive adhesive layer (2b')~~ a region (b') corresponding to the dicing ring-attaching region satisfies the relationship:

the adhesion to the dicing ring is lower than the adhesion to the ~~pressure-sensitive adhesive layer (2b')~~region (b').

6 (currently amended): A dicing/die-bonding film comprising a pressure-sensitive adhesive layer (2) on a supporting base material (1) and a die-bonding adhesive layer (3) on the pressure-sensitive adhesive layer (2),

wherein the die-bonding adhesive layer (3) is arranged as a work-attaching region (3a) on a part of the pressure-sensitive adhesive layer (2), and

a region (2aa) corresponding to the work-attaching region (3a) in the pressure sensitive adhesive layer (2) and ~~the other a~~ region (2bb) other than the region (a) are different in adhesion and satisfy the relationship:

the adhesion of the ~~pressure-sensitive adhesive layer (2a)~~region (a) is lower than the ~~adhesion of the pressure-sensitive adhesive layer (2b)~~region (b).

7 (currently amended): The dicing/die-bonding film according to claim 6, wherein ~~an~~ adhesion of the work-attaching region (3a) to the work and to the ~~pressure-sensitive adhesive layer (2a)~~region (a) satisfies the relationship:

the adhesion to the work is higher than the adhesion to the ~~pressure-sensitive adhesive layer (2a)~~region (a).

8 (currently amended): The dicing/die-bonding film according to claim 1, wherein the pressure-sensitive adhesive layer (2) ~~is formed from~~made of a radiation-curing pressure-sensitive adhesive, and the ~~pressure-sensitive adhesive layer (2a)~~region (a) corresponding to the work-attaching region (3a) is irradiated with radiations.

9 (currently amended): The dicing/die-bonding film according to claim 6, wherein the pressure-sensitive adhesive layer (2) ~~is formed from~~made of a radiation-curing pressure-sensitive adhesive, and the ~~pressure-sensitive adhesive layer (2a)~~region (a) corresponding to the work-attaching region (3a) is irradiated with radiations.

10 (currently amended): A method of fixing a chipped work, comprising the steps of: pressing a work onto ~~at~~ the work-attaching region of the die-bonding adhesive layer (3a) in the dicing/die-bonding film described in ~~any one of claims 1 to 9~~claim 1,

dicing the work into chips,

releasing the chipped work together with the work-attaching region of the die-bonding adhesive layer (3a) from a region (a) of the pressure-sensitive adhesive layer (2a) corresponding to the work-attaching region, and

fixing the chipped work to a semiconductor element via the work-attaching region of the die-bonding adhesive layer (3a).

11 (currently amended): A semiconductor device comprising a chipped work fixed onto a semiconductor element via the work-attaching region of the die-bonding adhesive layer (3a) by the method of fixing a chipped work as described in claim 10.

12 (new): A method of fixing a chipped work, comprising the steps of:
pressing a work onto the work-attaching region of the die-bonding adhesive layer in the dicing/die-bonding film set forth in claim 6,

dicing the work into chips,

releasing the chipped work together with the work-attaching region of the die-bonding adhesive layer from the region (a) of the pressure-sensitive adhesive layer, and

fixing the chipped work to a semiconductor element via the work-attaching region of the die-bonding adhesive layer.

13 (new): The method according to claim 10, wherein the pressure-sensitive adhesive layer is made of a radiation-curing pressure-sensitive adhesive, and the region (a) is irradiated with radiations.

14 (new): The method according to claim 12, wherein the pressure-sensitive adhesive layer is made of a radiation-curing pressure-sensitive adhesive, and the region (a) is irradiated with radiations.